

Abstract

The invention relates to a process for joining substrates
5 having electrical, semiconducting, mechanical and/or optical
components, and to a composite element.

The process is to be suitable for the substrates which are to
be joined substantially irrespective of material and in
10 particular also for sensitive substrates, is to have a high
chemical and physical stability and/or is to produce a hermetic
cavity.

According to the invention, a raised frame, in particular
15 formed from anodically bondable glass, is applied by
evaporation coating to one of the two substrates in order to
serve as a joining element.